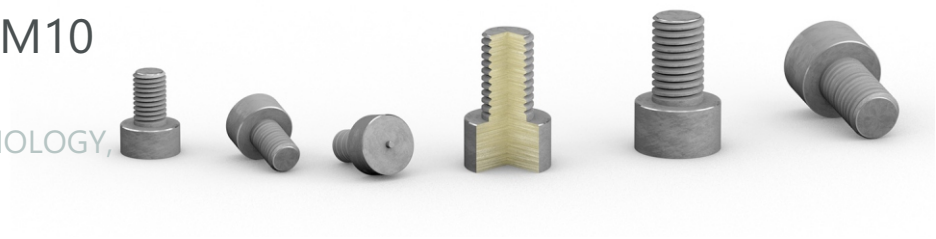
MTCON NECTIVITY

# POWER TOWER M10

EXTERNAL THREAD,
SMD SOLDERING TECHNOLOGY,
WITH CENTERING



## COMMERCIAL DATA

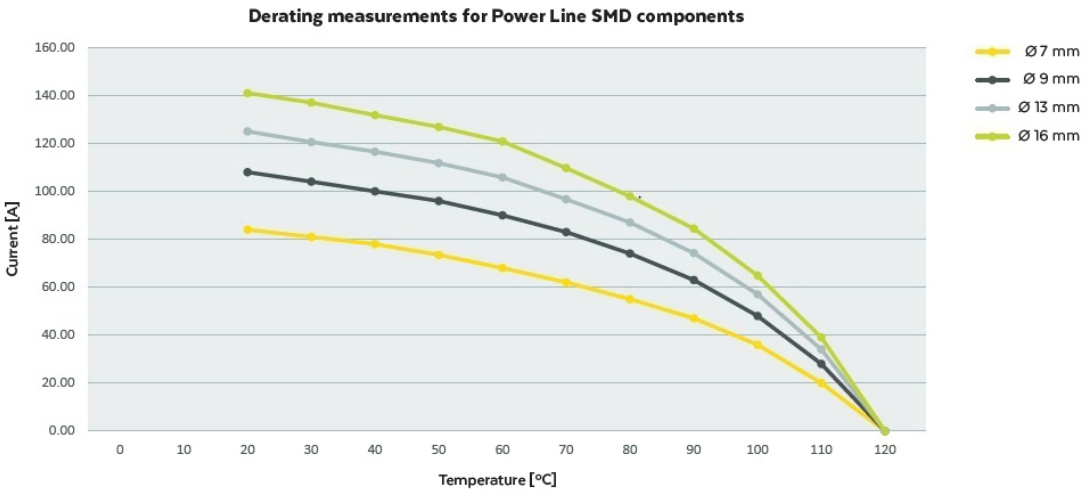
| | |
|---|---|
| **Part number** | **01.6.0012** |

| | |
|---|---|
| **Packing unit tape and reel - 1.6.0012.GU** | **not available yet** |
| **Customs tariff number** | **85369010** |
| **Mass** | **24,26 g** |
| **Country of origin** | **DE (Germany)** |

## TECHNICAL DATA

| | |
|---|---|
| **Current carrying capacity** | **ca. 250 A at 20°C / ca. 140 A at 85° C** |
| **Material** | **CuZn39Pb3** |
| **Surface** | **matt tinned** |

**Derating curves are snapshots under test condition!**
Testing was undertaken using two-layer circuit with 70µm copper.



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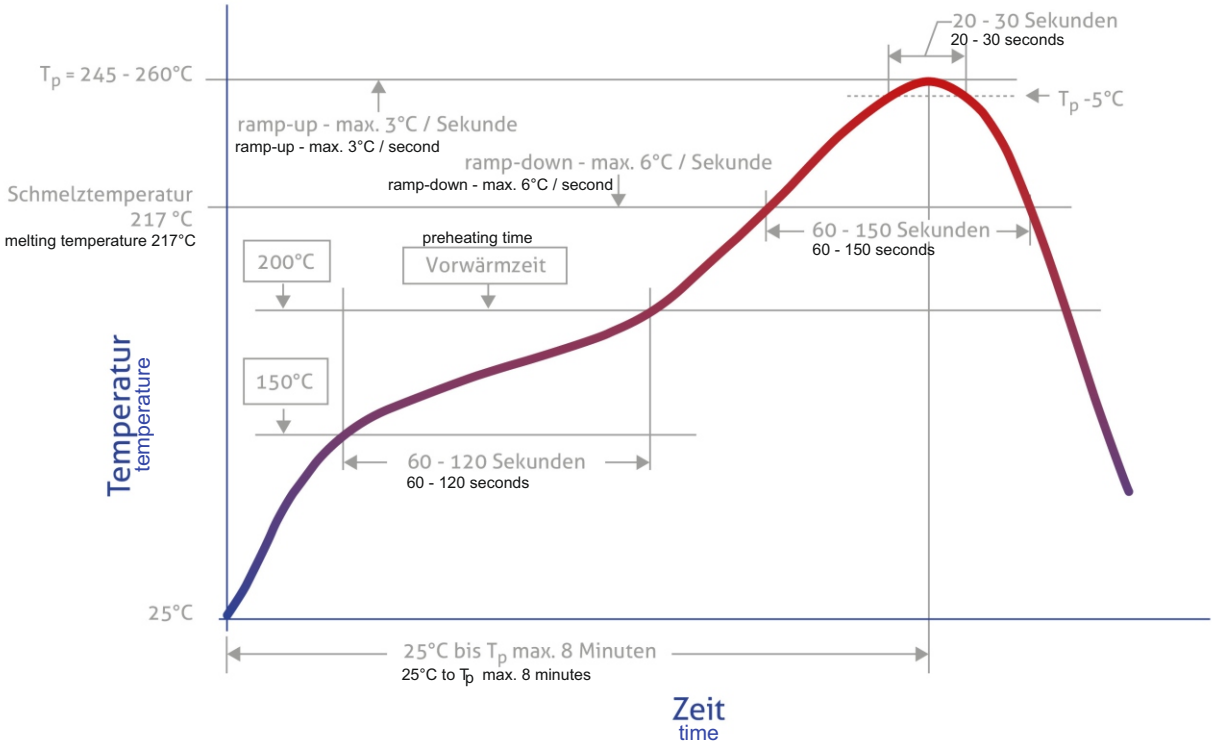
## PROCESSING

| | |
|---|---|
| **Torque** | **17,0 Nm** |
| **Solder paste thickness** | **150 µm** |
| **Operating temperature** | **-55°C to 150°C** |

## SOLDER PROFILE




### Reflow Temperatur in Abhängigkeit der Leiterplattendicke:

Reflow temperature depending on the thickness of printed ciruit board:

| Eigenschaften<br>properties | Volumen mm³ <350<br>volume mm³ < 350 | Volumen mm³ 350-2000<br>volume mm³ 350-2000 | Volumen mm³ >2000<br>volume mm³ > 2000 |
|---|---|---|---|
| Leiterplattendicke (Bleifrei) < 1.6 mm<br>PCB thickness (lead free) < 1.6.mm | 260 °C | 260 °C | 260 °C |
| Leiterplattendicke (Bleifrei) 1.6 mm - 2.5 mm<br>PCB thickness (lead free) 1.6.mm - 2.5 mm | 260 °C | 250 °C | 245 °C |
| Leiterplattendicke (Bleifrei) ≥ 2.5 mm<br>PCB thickness (lead free) ≥ 2.5 mm | 250 °C | 245 °C | 245 °C |

mit Bezug auf IPC/JEDEC J-STD-020D
regarding IPC/JEDEC J-STD-020D

## CONFORMITY

- RoHS compliant

RoHS COMPLIANT



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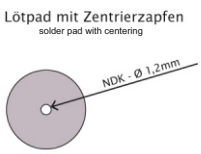
## TAPE AND REEL

not available yet

## LAYOUT



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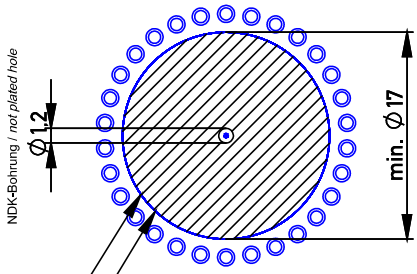
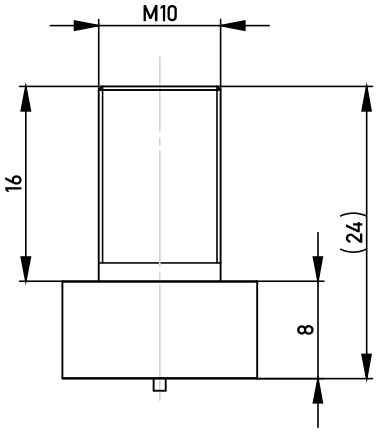
# LAYOUT

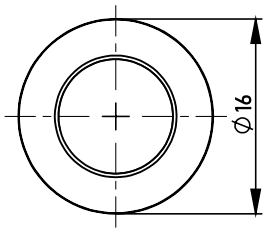
| Verpackung / *packaging* | Artikelnummer / *part number* |
|---|---|
| lose / *bulk* | 01.6.0012 |
| tape and reel | not available |




Empfehlung Lötpad / *recommendation solder pad*
vollflächiges Pad min. 0.5mm umlaufend größer als Element /
*full-face pad all round min. 0.5mm bigger than the element*

optionale DK-Bohrungen umlaufend um das Pad - für höhere Stromtragfähigkeit /
*optional plated holes around the pad - for higher current ratings*






RoHS COMPLIANT

Ausführung: SMD
Max. Drehmoment: 17,0 Nm
Gewicht: 24,26 g
Technische Änderungen vorbehalten

*execution: SMD*
*max. torque: 17,0 Nm*
*weight: 24,26 g*
*technical subject to change*

| | | | |
|---|---|---|---|
| Werkstoff / *material* | CuZn39Pb3 | Toleranz / *tolerance* | Maßstab / *scale* 2:1 |
| Oberfläche / *surface plating* | matt verzinnt / *mat tin-plated* | DIN ISO 2768-mH | Zeichnungsnummer / *drawing number* 01.6.0012 |
| Prozessbedingte Fehlstellen in Galvanik möglich! *imperfections during electro plating process possible!* | | all dimensions in mm | Benennung / description: Power Tower M10, SMD, 16er rund, mit Zentrierzapfen / **SMD, sixteens round, with centering pin** |

| | Datum / *date* | Name / *name* |
|---|---|---|
| Bearb. / *drawer* | 13.02.2014 | |
| gepr. / *auth.* | | |
| geän. / *mod.* | | |

| Index | Änderung / *modification* | Datum / *date* | Name / *name* |
|---|---|---|---|
| | REACH entfernen | 17.07.2018 | |
| A | Neuerstellung | 13.02.2014 | |

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